

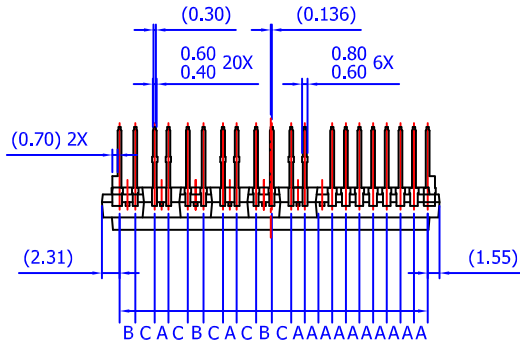
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



SPMCA-027 / PDD STD, SPM27-CA, DBC TYPE CASE MODFJ ISSUE O

DATE 31 JAN 2017

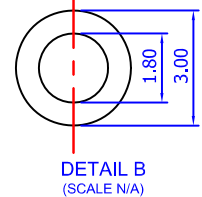
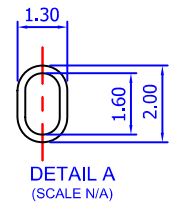
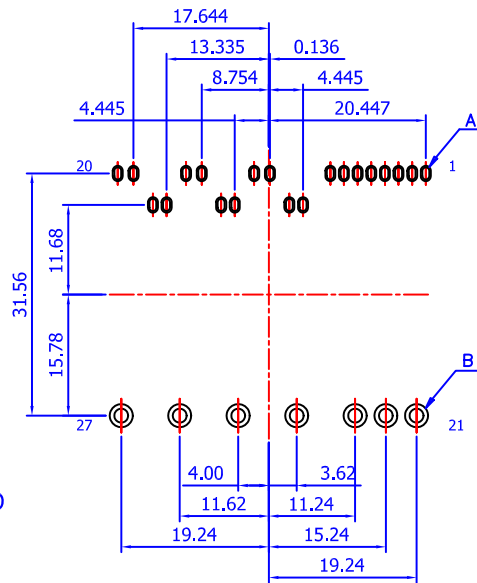
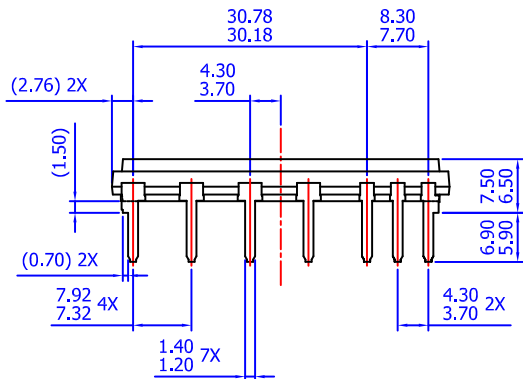
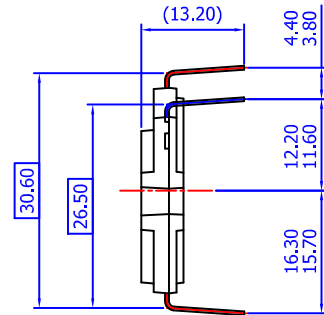
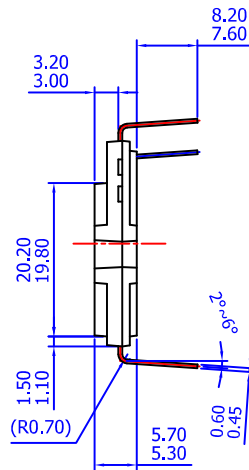
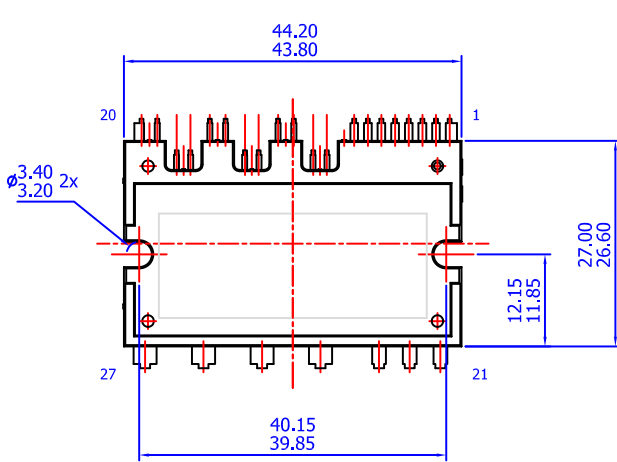


LEAD PITCH (TOLERANCE : ±0.30)

A : 1.778

B : 2.050

C : 2.531



- NOTES: UNLESS OTHERWISE SPECIFIED
 A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 B) ALL DIMENSIONS ARE IN MILLIMETERS
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 D) () IS REFERENCE

LAND PATTERN RECOMMENDATIONS

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SPMCA-027 / PDD STD, SPM27-CA, DBC TYPE	PAGE 1 OF 2

